



DMN6017SFV

PowerDI3333-8 (Type UX)

Product Summary

| BV _{DSS} | R _{DS(ON)} max | I _D max T _C = +25°C | | |
|-------------------|------------------------------|--|--|--|
| | 18mΩ @ V _{GS} = 10V | 35A | | |
| 60V | $20m\Omega @ V_{GS} = 4.5V$ | 34A | | |

Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- **Power Management Functions**
- **DC-DC Converters**

Features and Benefits

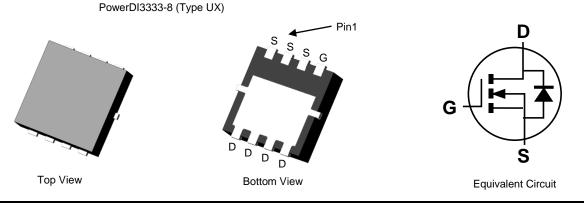
- Low R_{DS(ON)} Ensures on state losses are minimized
- Small form factor thermally efficient package enables higher density end products

60V N-CHANNEL ENHANCEMENT MODE MOSFET

- Occupies just 33% of the board area occupied by SO-8 enabling smaller end product
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: PowerDI[®]3333-8 (Type UX)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 3
- Weight: 0.030 grams (Approximate)



Ordering Information (Note 4)

| | Part Number | Case | Packaging | | | |
|--|--|-------------------------|-------------------|--|--|--|
| | DMN6017SFV-7 | PowerDI3333-8 (Type UX) | 2,000/Tape & Reel | | | |
| DMN6017SFV-13 PowerDI3333-8 (Type UX) 3,000/Tape & Ree | | 3,000/Tape & Reel | | | | |
| Notes: | Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. | | | | | |

2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



N67 = Product Type Marking Code YYWW = Date Code Marking \overline{YY} = Last Two Digits of Year (ex: 18 = 2018) WW = Week Code (01 to 53)

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Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit | |
|---|---|------------------|----------|----|
| Drain-Source Voltage | V _{DSS} | 60 | V | |
| Gate-Source Voltage | | V _{GSS} | ±20 | V |
| Continuous Drain Current (Note 7) V _{GS} = 10V | $T_{C} = +25^{\circ}C$ $T_{C} = +70^{\circ}C$ | ID | 35 28 | А |
| Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%) | | I _{DM} | 140 | А |
| Maximum Continuous Body Diode Forward Current (Note 7) | | Is | 20 | А |
| Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%) | I _{SM} | 140 | А | |
| Avalanche Current, L = 0.1mH (Note 8) | I _{AS} | 25 | А | |
| Avalanche Energy, L = 0.1mH (Note 8) | | E _{AS} | 32 | mJ |

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | | Symbol | Value | Unit |
|---|--------------|----------------------------------|-------------|------|
| Total Power Dissipation (Note 5) | | PD | 1.0 | W |
| Thermal Resistance, Junction to Ambient (Note 5) | Steady State | $R_{\theta JA}$ | 126 | °C/W |
| Total Power Dissipation (Note 6) | | PD | 2.0 | W |
| Thermal Resistance, Junction to Ambient (Note 6) Steady State | | $R_{\theta JA}$ | 62 | °C/W |
| Thermal Resistance, Junction to Case (Note 7) | | R _θ JC | 3.7 | C/W |
| Operating and Storage Temperature Range | | T _{J,} T _{STG} | -55 to +150 | °C |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| | | | _ | | | | |
|--|---------------------|-----|------|------|-------|--|--|
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
| OFF CHARACTERISTICS (Note 9) | | - | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 60 | — | — | V | $V_{GS} = 0V, I_D = 250 \mu A$ | |
| Zero Gate Voltage Drain Current | I _{DSS} | _ | _ | 1 | μA | $V_{DS} = 48V, V_{GS} = 0V$ | |
| Gate-Source Leakage | IGSS | — | — | ±100 | nA | $V_{GS} = \pm 20V, V_{DS} = 0V$ | |
| ON CHARACTERISTICS (Note 9) | | | | | | | |
| Gate Threshold Voltage | V _{GS(TH)} | 1 | — | 3 | V | $V_{DS} = V_{GS}$, $I_D = 250 \mu A$ | |
| Static Drain-Source On-Resistance | | | 12 | 18 | mΩ | $V_{GS} = 10V, I_D = 6A$ | |
| | R _{DS(ON)} | _ | 13 | 20 | 11152 | $V_{GS} = 4.5V, I_D = 4A$ | |
| Diode Forward Voltage | V _{SD} | | 0.7 | 1 | V | $V_{GS} = 0V, I_S = 1A$ | |
| DYNAMIC CHARACTERISTICS (Note 10) | | | | | | | |
| Input Capacitance | Ciss | | 2711 | | рF | | |
| Output Capacitance | Coss | _ | 152 | | pF | V _{DS} = 15V, V _{GS} = 0V, f = 1MHz | |
| Reverse Transfer Capacitance | C _{rss} | | 126 | | рF | | |
| Gate Resistance | Rg | | 1.4 | — | Ω | $V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$ | |
| Total Gate Charge (V _{GS} = 4.5V) | Qg | _ | 26 | | nC | | |
| Total Gate Charge (V _{GS} = 10V) | Qg | | 55 | | nC | V _{DS} = 48V, I _D = 6A | |
| Gate-Source Charge | Q _{gs} | _ | 6.2 | | nC | VDS = 48V, ID = 6A | |
| Gate-Drain Charge | Q _{gd} | | 8.5 | — | nC | | |
| Turn-On Delay Time | t _{D(ON)} | _ | 4.9 | — | ns | | |
| Turn-On Rise Time | t _R | _ | 5.4 | _ | ns | $V_{DD} = 30V, V_{GS} = 10V,$ $R_G = 3.3\Omega, I_D = 6A$ | |
| Turn-Off Delay Time | t _{D(OFF)} | _ | 38.2 | _ | ns | | |
| Turn-Off Fall Time | tF | | 11 | _ | ns | | |
| Reverse Recovery Time | t _{RR} | _ | 16.6 | _ | ns | | |
| Reverse Recovery Charge | Q _{RR} | | 10.3 | _ | nC | $I_F = 6A$, di/dt = 100A/µs | |

Notes:

Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.

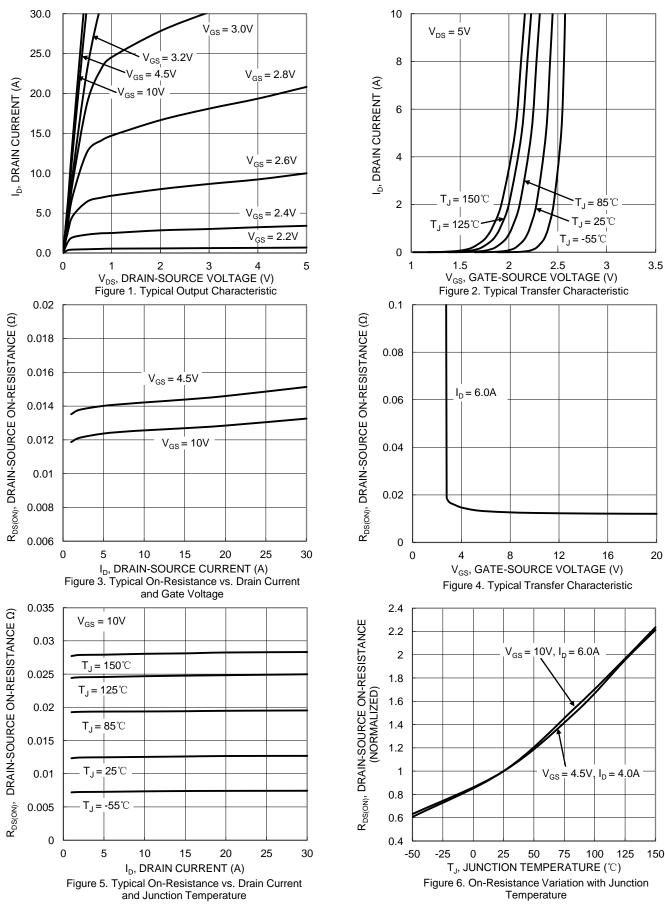
7. Thermal resistance from junction to soldering point (on the exposed drain pad).

8. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep $T_J = +25^{\circ}C$.

Short duration pulse test used to minimize self-heating effect.
Guaranteed by design. Not subject to product testing.

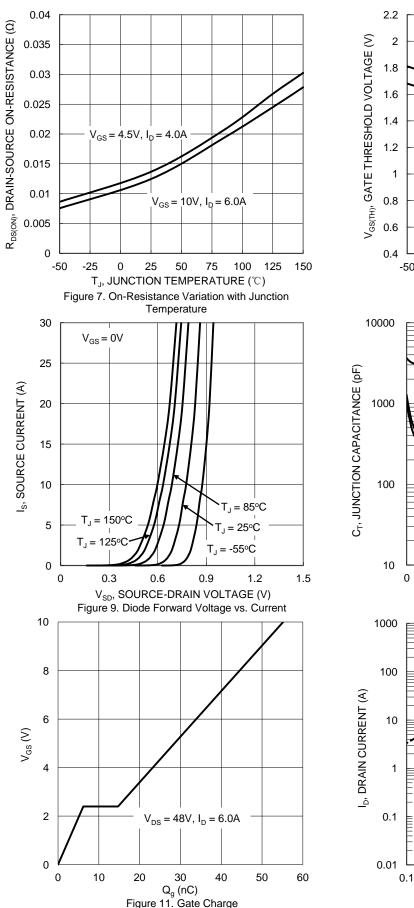


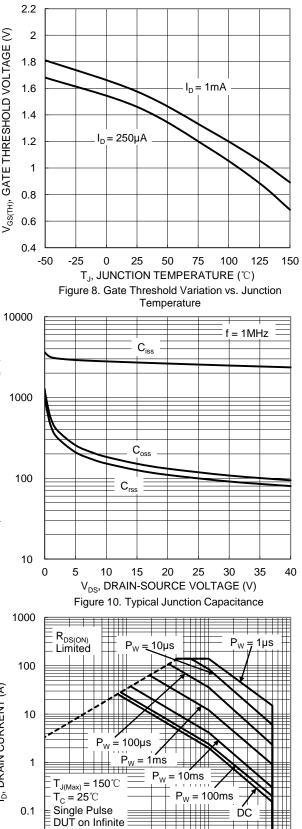
DMN6017SFV











Heatsink $V_{GS} = 10V$

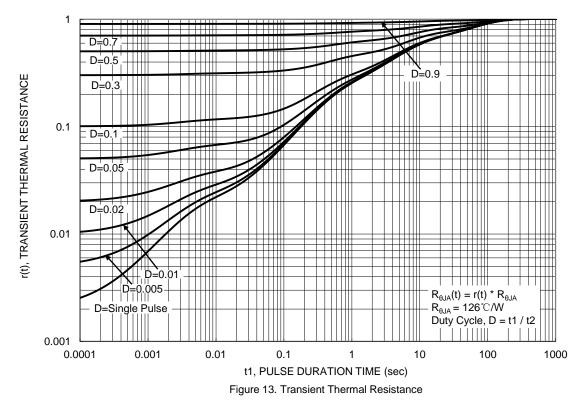
1 10 V_{DS}, DRAIN-SOURCE VOLTAGE (V)

Figure 12. SOA, Safe Operation Area

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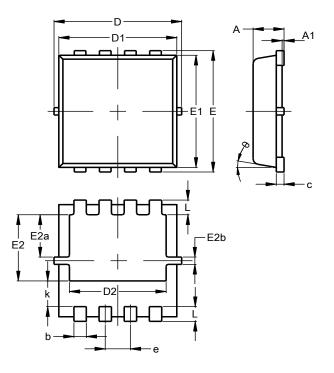




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8 (Type UX)

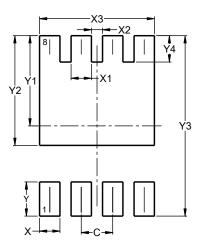


| PowerDI3333-8 | | | | | | |
|---------------|----------------------|----------------|------|--|--|--|
| (Type UX) | | | | | | |
| Dim | Min | Max | Тур | | | |
| Α | 0.75 | 0.85 | 0.80 | | | |
| A1 | 0.00 | 0.05 | | | | |
| b | 0.25 | 0.40 | 0.32 | | | |
| c | 0.10 | 0.25 | 0.15 | | | |
| D | 3.20 | 3.20 3.40 3.30 | | | | |
| D1 | 2.95 | 3.15 | 3.05 | | | |
| D2 | 2.30 | 2.70 | 2.50 | | | |
| Е | 3.20 | 3.40 | 3.30 | | | |
| E1 | 2.95 | 3.15 | 3.05 | | | |
| E2 | 1.60 | 2.00 | 1.80 | | | |
| E2a | 0.95 | 1.35 | 1.15 | | | |
| E2b | 0.10 | 0.30 | 0.20 | | | |
| е | 0.65 BSC | | | | | |
| k | 0.50 | 0.90 | 0.70 | | | |
| L | 0.30 | 0.50 | 0.40 | | | |
| θ | 0° | 12° | 10° | | | |
| All | All Dimensions in mm | | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8 (Type UX)



| Dimensions | Value (in mm) | | | |
|------------|---------------|--|--|--|
| С | 0.650 | | | |
| Х | 0.420 | | | |
| X1 | 0.420 | | | |
| X2 | 0.230 | | | |
| X3 | 2.370 | | | |
| Y | 0.700 | | | |
| Y1 | 1.850 | | | |
| Y2 | 2.250 | | | |
| Y3 | 3.700 | | | |
| Y4 | 0.540 | | | |



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